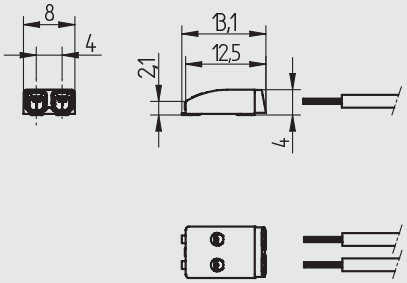
SMD-Terminal block - Mini-Flex



General note: It is recommended to make an electrical connection between both poles of each polarity on the solder pad.

pkg.	wt.	part no.
1200	0,4 g	**46.132.**1001.50

SMD-Terminal block - Mini-Flex with push wire contacts and contact opening function

2 pole

Direct insertion of solid and stranded, tinned wire ends and finely stranded conductors by using the contact opening function

Contact opening function - also for release of already inserted wires

Mounting and wiring position: PCB top side

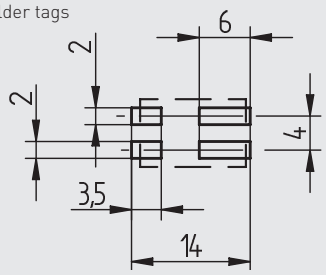
Machine-compatible "tape-and-reel" packaging

Fixing: Lead-free reflow soldering according to DIN EN 610760-1, section 6

Material: Housing: PPA, white
Contact material: CuNi
Contact surface: hot-dipped tinned 5-10 µm

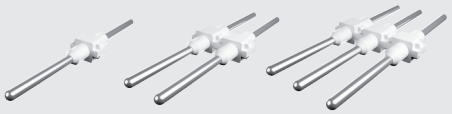
To operate the contact opening function, we recommend the use of our tools **46.131**.U801.89 or **46.131**.-398.50

Recommended dimensions for solder tags

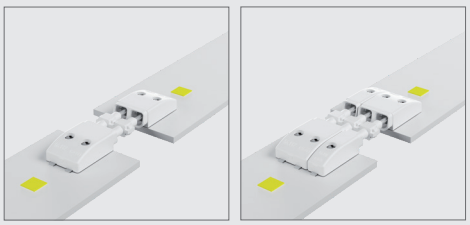


LED-LINE | Uimp 2,5 kV | 0,2 - 0,75mm² AWG 24-18 | 0,2 - 0,5mm² AWG 24-20 | 0,2 - 0,75mm² AWG 24-18 | 8 +1 mm | CAD

Accessories:
SMD Mini-Flex-B2B-connector. For connecting PCBs.
Connectors are available in 26 mm (U701), 28 mm (U702) and 30 mm (U703) length.



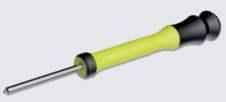
46.131 **46.132** **46.133**



Contact opening tool
For opening the contacts when using fine-stranded conductors or to remove already inserted conductors.

46.131.-398.50

Integrated stripping function
for wire ends cut but not stripped



46.131.U801.89

LED - Light and connection technology

SMD-Terminal block - Mini-Flex
General technical information

Connection data	
Connection technology	Push wire contacts
Solid wires	0.20 - 0.75 mm², AWG 24-18
Stranded, tinned wires	0.20 - 0.5 mm², AWG 24-20
Stranded wires	0.20 - 0.75 mm², AWG 24-18
Strip length	8 +1 mm
Conductor entry angle to the PCB	0°
Wire release function by	Contact opening tool

Pull-out force according to DN 60999-1	
0.2 mm²	min. 10 N
0.34 mm²	min. 15 N
0.5 mm²	min. 20 N
0.75 mm²	min. 30 N
Insertion force	max. 10 N

Geometrical data	
Pin spacing	4 mm / 0.16 inch
Width	8 mm / 0.32 inch
Height	4 mm / 0.16 inch
Depth	13.1 mm / 0.52 inch
Reel diameter of tape-and-reel packaging	330 mm (13")
Reel width	24 mm
Pitch distance	12 mm
Packaging unit tape-and-reel	1.200
Packaging unit cardboard	15.600 (13 reels)

Material data	
Insulating material group	I
Insulating material	PPA, white
PTI	600
Flammability class, based on UL 94	V0
Contact material	CuNi
Contact surface	hot-dipped tinned 5-10 µm

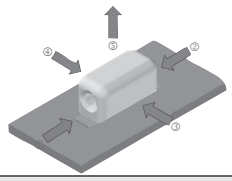
Mechanical data	
Mounting position	PCB top side
Mounting type	Lead-free reflow soldering

Temperature data	
Marginal temperatures	-40 °C to + 150 °C
Ambient temperature	-40 °C to + 105 °C
T-classification according to IEC 60998-1 para. 12	120°

Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1	
Rated voltage (III / 3)	63 V
Rated impulse voltage (III / 3)	2.5 kV
Rated voltage (III / 2)	160 V
Rated impulse voltage (III / 2)	2.5 kV
Rated voltage (II / 2)	320 V
Rated impulse voltage (II / 2)	2.5 kV
Rated current	9 A

Rated data according to UL 1977	
Rated voltage UL 1977	320 V
Rated current UL 1977	9 A

Country specific certificates	
VDE ENEC	EN 60947
UL	cURus, File No. E-365006

Shear forces according to DIN 62137-1-2 in [N]	
Direction 1 +2 shear force along	>70
Direction 3 + 4 shear force across	>30
Direction 5 pull-off force	>30

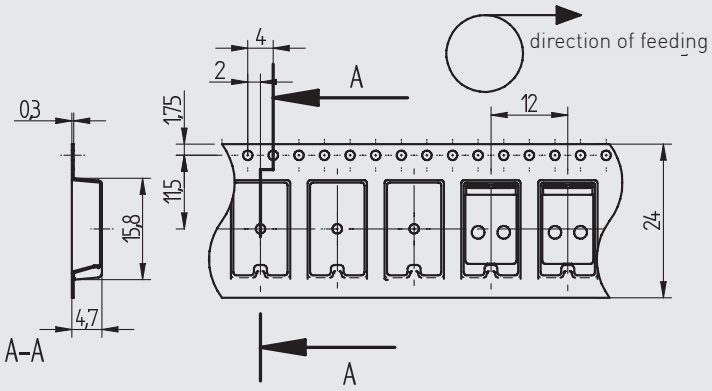
LED - Light and connection technology

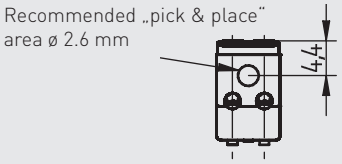
SMD-Terminal block - Mini-Flex
Instructions for processing

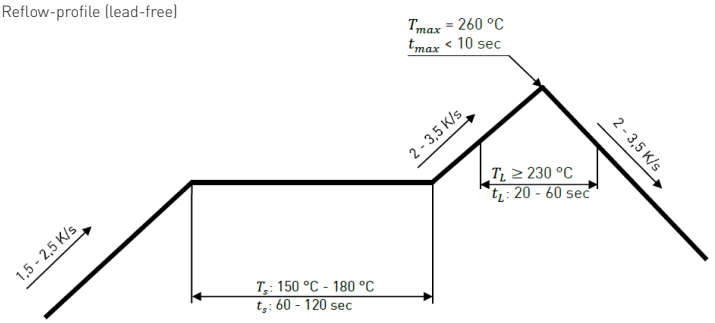
Instructions for soldering process

Suitable for leadfree-reflow-profiles according to DIN EN 61760-1 respective DIN EN 60068-2-58 up to peak-temperature of max. 260°C.
Due to different application-specific parameters (component arrangement and alignment, soldering system, solder paste), it is recommended to use test runs to determine a suitable profile under production conditions.

Depending on the SMD soldering process and associated parameters a minor discoloration might occur. However, this will not influence the functionality.





Storage time	Solderability up to 6 months when stored between -5°C and +40°C and rel. humidity between 10...60% r H. After a storage time of 6 months, solderability has to be checked according to J-STD-002D or DIN EN 60068-2-58:2016.
max. allowed number of reflow-processes	3
Reflow-profile	Reflow-profile (lead-free) 
Solderability	Solderability of components is checked by wetting test according to J-STD-002D
Assembly method	SMD, according to drawing
Recommended solder stencil thickness	100 - 150 µm (recommendation BJB 150)